

ABSTRACT OF THE DISCLOSURE

Die bonding equipment for fine pitch ball grid array package includes: a semiconductor chip pickup stage for inspecting a status of a loaded semiconductor chip and a corresponding position thereof; an alignment stage on which the semiconductor chip fixed on a mount head is aligned; a chip transfer unit for transferring the semiconductor chip from the semiconductor chip pickup stage to the alignment stage; a guide rail for guiding a mount tape frame; a status inspecting unit disposed at a selected position over the guide rail, for inspecting a status and a position of the land pattern on the mount tape frame; and a bonding unit for bonding the land pattern to the semiconductor chip which is mounted on the mount head. The equipment only bonds semiconductor chips (good or defective) to lands patterns having the same status (good or defective).